

Heraeus

NEW!



AgCoat™ Prime: Gold-Coated Silver Bonding Wire

World's First Gold-Coated Silver Bonding Wire for Semiconductor Technology

Heraeus Electronics innovation team has created the world's first gold-coated silver wire for memory devices in the semiconductor industry. AgCoat™ Prime is a silver alloy bonding wire coated with a layer of gold which provides the bondability and reliability of gold wire.

The specifications for AgCoat™ Prime are closely aligned with the characteristics of gold bonding wire, meaning no inert gas is required and no additional investment or production changes.

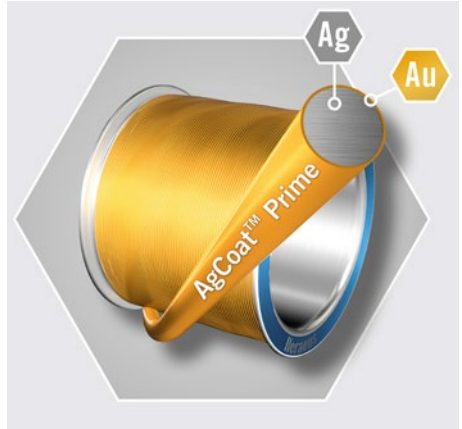
AgCoat™ Prime is essentially a plug and play solution for your ball bonding process and a cost-efficient substitute that will relieve the stress of rising costs.

AgCoat™ Prime: Gold-Coated Silver Bonding Wire

The Perfect Match of Performance and Cost

AgCoat™ Prime key benefits

- Plug and play
- Cost effective substitution for gold wire
- No CAPEX investment needed
- Eliminates the need of protection gas and kit during FAB formation



Note:

AgCoat™ Prime has gone through rigorous test internally and externally to meet the standard industry requirement. It has demonstrated reliable result by passing various qualification testing in our customer's laboratory. The product is preparing to enter the scale-up stage, and mass production is expected to be available in 2020.

Interested to discuss more with our expert?

Heraeus Electronics

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